PROCESS CHANGE NOTICE  PCN0119
FineLine BGA™ Package Molding Compound Change

Change Description:
ASAT Hong Kong will change the FineLine BGA™ package molding compound from Shin Etsu to Nitto HC-100. This change will not affect the package thickness specification, overall package dimensions, or the moisture rating for these packages.

Reason For Change:
The FineLine BGA™ package molding compound is changing from Shin Etsu to Nitto HC-100 to improve package coplanarity during high-temperature reflow.

Products Affected:
All MAX, FLEX, APEX, and ACEX family FineLine BGA™ packages assembled at ASAT Hong Kong.

Initial products affected will include:

<table>
<thead>
<tr>
<th>EPF10K100E 484-Ball FineLine BGA™</th>
<th>EPF10K200S 672-Ball FineLine BGA™</th>
</tr>
</thead>
<tbody>
<tr>
<td>EPF10K130E 484-Ball FineLine BGA™</td>
<td>EPF10K200E 672-Ball FineLine BGA™</td>
</tr>
<tr>
<td>EP20K200E  484-Ball FineLine BGA™</td>
<td>EP20K200E   672-Ball FineLine BGA™</td>
</tr>
<tr>
<td></td>
<td>EP20K300E   672-Ball FineLine BGA™</td>
</tr>
</tbody>
</table>

Product Traceability and Transition Dates:
Product assembled with Nitto-HC100 molding compound will begin shipping on or after February 15, 2002 and can be distinguished by the topside marked date code of 0213 or later.

Contact:
Qualification reports are available upon request. For additional information regarding the changes described in this document, please contact the Altera Customer Quality Engineering Department at (408) 544-6933.